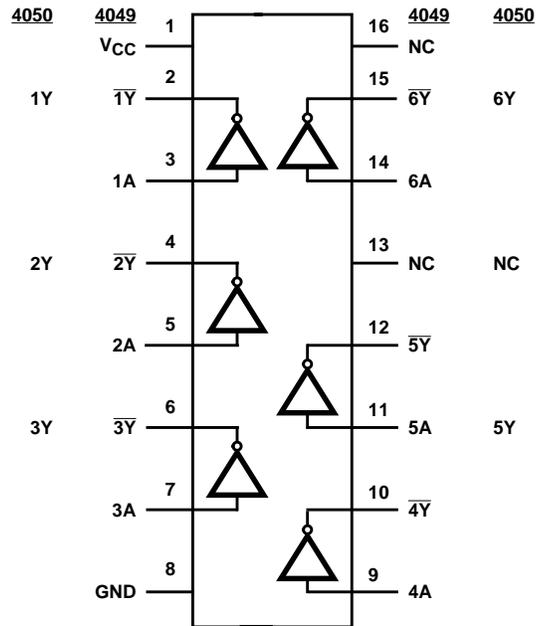




**Functional Diagram**

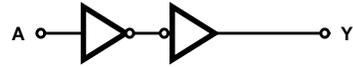


**Logic Diagrams**

HC4049



HC4050



# CD54HC4049, CD74HC4049, CD54HC4050, CD74HC4050

## Absolute Maximum Ratings

DC Supply Voltage, $V_{CC}$ .....	-0.5V to 7V
Input Voltage Range .....	-0.5V to 16V
DC Input Diode Current, $I_{IK}$	
For $V_I < -0.5V$ .....	-20mA
DC Output Diode Current, $I_{OK}$	
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$ .....	$\pm 20mA$
DC Output Source or Sink Current per Output Pin, $I_O$	
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$ .....	$\pm 25mA$
DC $V_{CC}$ or Ground Current, $I_{CC}$ or $I_{GND}$ .....	$\pm 50mA$

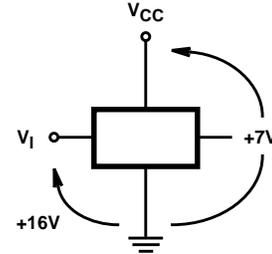
## Thermal Information

Package Thermal Impedance, $\theta_{JA}$ (see Note 1):	
E (PDIP) Package .....	67°C/W
M (SOIC) Package .....	73°C/W
NS (SOP) Package .....	64°C/W
PW (TSSOP) Package .....	108°C/W
Maximum Junction Temperature (Hermetic Package or Die) .....	175°C
Maximum Junction Temperature (Plastic Package) .....	150°C
Maximum Storage Temperature Range .....	-65°C to 150°C
Maximum Lead Temperature (Soldering 10s) .....	300°C
	(SOIC - Lead Tips Only)

## Operating Conditions

Temperature Range ( $T_A$ ) .....	-55°C to 125°C
Supply Voltage Range, $V_{CC}$	
HC Types .....	.2V to 6V
HCT Types .....	4.5V to 5.5V
DC Input Voltage, $V_I$ .....	.0V to 15V
DC Output Voltage, $V_O$ .....	0V to $V_{CC}$
Input Rise and Fall Time	
2V .....	1000ns (Max)
4.5V .....	500ns (Max)
6V .....	400ns (Max)

**VOLTAGE  
RELATIONSHIPS  
MAXIMUM LIMITS**



**CAUTION:** Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

- The package thermal impedance is calculated in accordance with JESD 51-7.

## DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		$V_{CC}$ (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS	
		$V_I$ (V)	$I_O$ (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX		
<b>HC TYPES</b>													
High Level Input Voltage	$V_{IH}$	-	-	2	1.5	-	-	1.5	-	1.5	-	V	
				4.5	3.15	-	-	3.15	-	3.15	-	V	
				6	4.2	-	-	4.2	-	4.2	-	V	
Low Level Input Voltage	$V_{IL}$	-	-	2	-	-	0.5	-	0.5	-	0.5	V	
				4.5	-	-	1.35	-	1.35	-	1.35	V	
				6	-	-	1.8	-	1.8	-	1.8	V	
High Level Output Voltage CMOS Loads	$V_{OH}$	$V_{IH}$ or $V_{IL}$	-0.02	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
			-0.02	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
			-0.02	-0.02	6	5.9	-	-	5.9	-	5.9	-	V
High Level Output Voltage TTL Loads	$V_{OH}$	$V_{IH}$ or $V_{IL}$	-4	-4	4.5	3.98	-	-	3.84	-	3.7	-	V
			-5.2	-5.2	6	5.48	-	-	5.34	-	5.2	-	V
Low Level Output Voltage CMOS Loads	$V_{OL}$	$V_{IH}$ or $V_{IL}$	0.02	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	0.02	6	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads	$V_{OL}$	$V_{IH}$ or $V_{IL}$	4	4	4.5	-	-	0.26	-	0.33	-	0.4	V
			5.2	5.2	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	$I_I$	$V_{CC}$ or GND	-	6	-	-	$\pm 0.1$	-	$\pm 1$	-	$\pm 1$	$\mu A$	
		15	-	6	-	-	$\pm 0.5$	-	$\pm 5$	-	$\pm 5$	$\mu A$	

**CD54HC4049, CD74HC4049, CD54HC4050, CD74HC4050**

**DC Electrical Specifications (Continued)**

PARAMETER	SYMBOL	TEST CONDITIONS		V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
Quiescent Device Current	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	6	-	-	2	-	20	-	40	μA

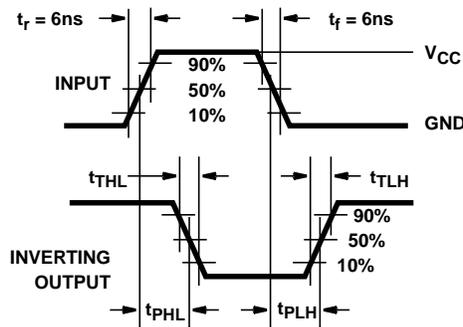
**Switching Specifications** Input t<sub>r</sub>, t<sub>f</sub> = 6ns

PARAMETER	SYMBOL	TEST CONDITIONS	V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HC TYPES</b>											
Propagation Delay, nA to nY HC4049 nA to nY HC4050	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	85	-	105	-	130	ns
			4.5	-	-	17	-	21	-	26	ns
			6	-	-	14	-	18	-	22	ns
Transition Times (Figure 1)	t <sub>TLH</sub> , t <sub>THL</sub>	C <sub>L</sub> = 50pF	2	-	-	75	-	95	-	110	ns
			4.5	-	-	15	-	19	-	22	ns
			6	-	-	13	-	16	-	19	ns
Input Capacitance	C <sub>I</sub>	-	-	-	-	10	-	10	-	10	pF
Power Dissipation Capacitance (Notes 2, 3)	C <sub>PD</sub>	-	5	-	35	-	-	-	-	-	pF

**NOTES:**

- C<sub>PD</sub> is used to determine the dynamic power consumption, per gate.
- P<sub>D</sub> = V<sub>CC</sub><sup>2</sup> f<sub>i</sub> (C<sub>PD</sub> + C<sub>L</sub>) where f<sub>i</sub> = Input Frequency, C<sub>L</sub> = Output Load Capacitance, V<sub>CC</sub> = Supply Voltage.

**Test Circuit and Waveform**



**FIGURE 1. HC AND HCU TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC**

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8681901EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8681901EA CD54HC4049F3A	<a href="#">Samples</a>
5962-8682001EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8682001EA CD54HC4050F3A	<a href="#">Samples</a>
CD54HC4049F3A	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8681901EA CD54HC4049F3A	<a href="#">Samples</a>
CD54HC4050F3A	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8682001EA CD54HC4050F3A	<a href="#">Samples</a>
CD74HC4049E	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC4049E	<a href="#">Samples</a>
CD74HC4049EE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC4049E	<a href="#">Samples</a>
CD74HC4049M	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4049M	<a href="#">Samples</a>
CD74HC4049M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4049M	<a href="#">Samples</a>
CD74HC4049M96E4	ACTIVE	SOIC	D	16	2500	TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>
CD74HC4049M96G4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4049M	<a href="#">Samples</a>
CD74HC4049MT	ACTIVE	SOIC	D	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4049M	<a href="#">Samples</a>
CD74HC4049NS	ACTIVE	SO	NS	16	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM		HC4049M	<a href="#">Samples</a>
CD74HC4049NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4049M	<a href="#">Samples</a>
CD74HC4049NSRE4	ACTIVE	SO	NS	16	2000	TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>
CD74HC4049PW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ4049	<a href="#">Samples</a>
CD74HC4049PWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ4049	<a href="#">Samples</a>
CD74HC4050E	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC4050E	<a href="#">Samples</a>
CD74HC4050EE4	ACTIVE	PDIP	N	16	25	TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>
CD74HC4050M	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4050M	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD74HC4050M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4050M	<a href="#">Samples</a>
CD74HC4050ME4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4050M	<a href="#">Samples</a>
CD74HC4050MT	ACTIVE	SOIC	D	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4050M	<a href="#">Samples</a>
CD74HC4050NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4050M	<a href="#">Samples</a>
CD74HC4050PW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ4050	<a href="#">Samples</a>
CD74HC4050PWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ4050	<a href="#">Samples</a>
CD74HC4050PWRG4	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ4050	<a href="#">Samples</a>
CD74HC4050PWT	ACTIVE	TSSOP	PW	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ4050	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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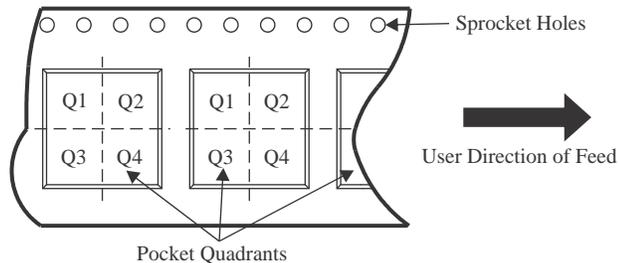
**OTHER QUALIFIED VERSIONS OF CD54HC4049, CD54HC4050, CD74HC4049, CD74HC4050 :**

- Catalog : [CD74HC4049](#), [CD74HC4050](#)
- Military : [CD54HC4049](#), [CD54HC4050](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


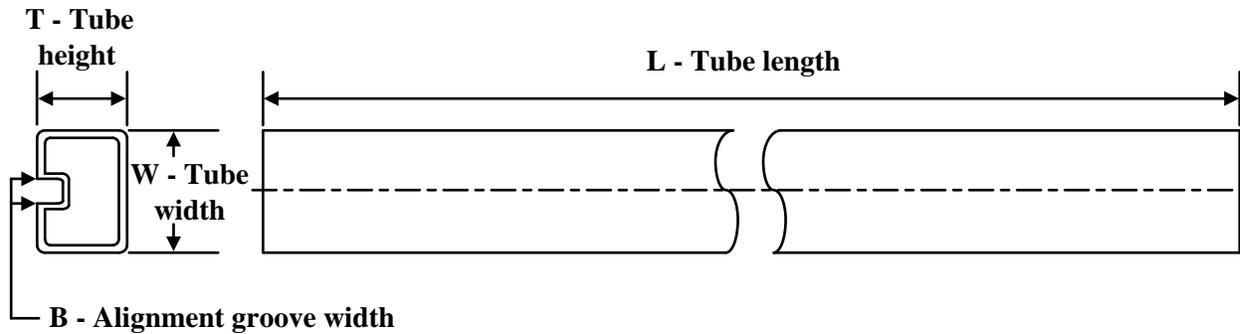
\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC4049M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC4049NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD74HC4049PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC4050M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC4050NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD74HC4050PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC4050PWT	TSSOP	PW	16	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC4049M96	SOIC	D	16	2500	340.5	336.1	32.0
CD74HC4049NSR	SO	NS	16	2000	356.0	356.0	35.0
CD74HC4049PWR	TSSOP	PW	16	2000	356.0	356.0	35.0
CD74HC4050M96	SOIC	D	16	2500	340.5	336.1	32.0
CD74HC4050NSR	SO	NS	16	2000	356.0	356.0	35.0
CD74HC4050PWR	TSSOP	PW	16	2000	356.0	356.0	35.0
CD74HC4050PWT	TSSOP	PW	16	250	356.0	356.0	35.0

**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
CD74HC4049E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC4049E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC4049EE4	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC4049EE4	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC4049M	D	SOIC	16	40	507	8	3940	4.32
CD74HC4049NS	NS	SOP	16	50	530	10.5	4000	4.1
CD74HC4049PW	PW	TSSOP	16	90	530	10.2	3600	3.5
CD74HC4050E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC4050E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC4050M	D	SOIC	16	40	507	8	3940	4.32
CD74HC4050ME4	D	SOIC	16	40	507	8	3940	4.32
CD74HC4050PW	PW	TSSOP	16	90	530	10.2	3600	3.5

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